

FIG. 5A

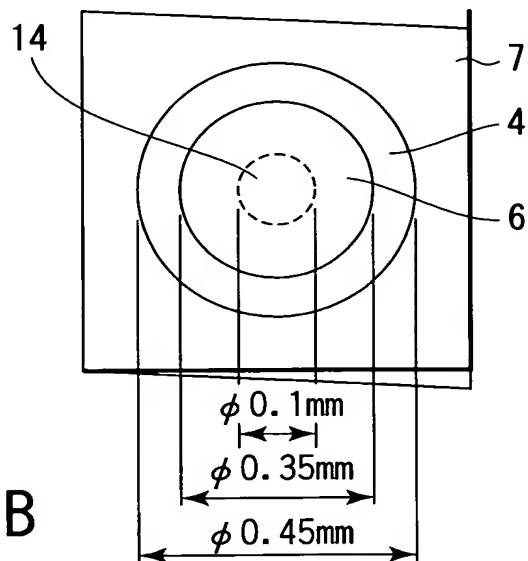


FIG. 5B

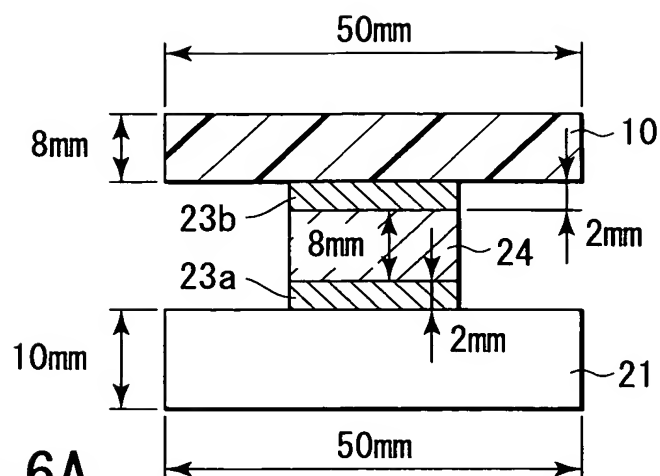


FIG. 6A

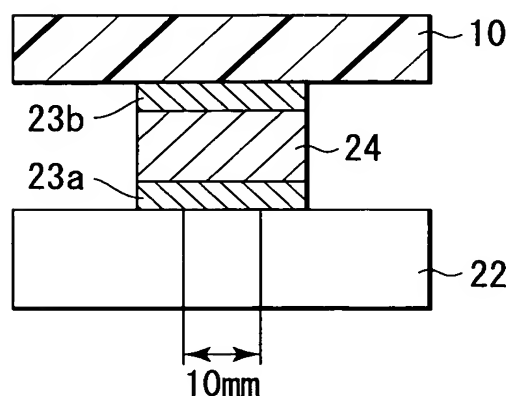


FIG. 6B

	Electronic component	Cu electrode	Solder	Printed board circuit
Mass density (N/mm ³)	1.96 * e-5	7.85 * e-5	19.6 * e-5	8.34 * e-5
Yong' s modulus (MPa)	20500	106700	22800	20000
Thermal expansion coefficient (ppm/°C)	1.3 * e-5	1.65 * e-5	6.5 * e-5	2.5 * e-5
Poisson' s ratio	0.3	0.34	0.19	0.39

FIG. 6C

